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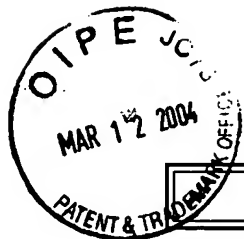
Electronic Filing System (EFS) Data  
Electronic Patent Application Submission  
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EFS ID: 57016  
Application ID: 10706468  
Title of Invention: SEMICONDUCTOR PACKAGE  
WITH CHAMFERED CORNERS  
AND METHOD OF  
MANUFACTURING THE SAME  
First Named Inventor: Sung Yang  
Domestic/Foreign Application: Domestic Application  
Filing Date: 2003-11-12  
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Submission Type: Information Disclosure  
Statement  
Filing Type:  
Confirmation number: 6744  
Attorney Docket Number: AMKOR095A



Total Fees Authorized:


Digital Certificate Holder: cn=Mark B. Garred,ou=Registered Attorneys,ou=Patent and Trademark  
Office,ou=Department of Commerce,o=U.S. Government,c=US  
Certificate Message Digest: e950f9d829755777902cf898e92f7d2805329597



# TRANSMITTAL

Electronic Version v1.1

Stylesheet Version v1.1.0

<b>Title of Invention</b>	<b>SEMICONDUCTOR PACKAGE WITH CHAMFERED CORNERS AND METHOD OF MANUFACTURING THE SAME</b>									
<p>Application Number: 10/706468 </p> <p>Date: 2003-11-12</p> <p>First Named Applicant: Sung Jin Yang</p> <p>Confirmation Number: 6744</p> <p>Attorney Docket Number: AMKOR095A</p>										
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>Mark B. Garred Registered Number: 34,823</td><td>/mbg/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	Mark B. Garred Registered Number: 34,823	/mbg/	Attorney		
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Mark B. Garred Registered Number: 34,823	/mbg/	Attorney								
<table><tr><td>Documents being submitted</td><td>Files</td></tr><tr><td>us-ids</td><td>ids2-usidst.xml</td></tr><tr><td></td><td>us-ids.dtd</td></tr><tr><td></td><td>us-ids.xsl</td></tr></table>			Documents being submitted	Files	us-ids	ids2-usidst.xml		us-ids.dtd		us-ids.xsl
Documents being submitted	Files									
us-ids	ids2-usidst.xml									
	us-ids.dtd									
	us-ids.xsl									
<b>Comments</b>										



## ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of  
Invention

SEMICONDUCTOR PACKAGE WITH CHAMFERED  
CORNERS AND METHOD OF MANUFACTURING THE  
SAME

Application Number: 10/706468  
Confirmation Number: 6744  
First Named Applicant: Sung Yang  
Attorney Docket Number: AMKOR095A



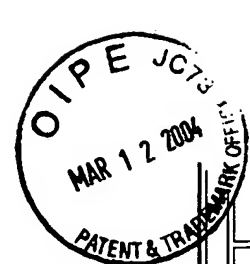
Art Unit: 2811

Search string: ( 5221642 or 5250841 or 5252853 or 5258094  
or 5266834 or 5273938 or 5278446 or 5277972  
or 5279029 or 5281849 or 5294897 or 5327008  
or 5332864 or 5336931 or 5335771 or 5343076  
or 5358905 or 5365106 or 5381042 or 5391439  
or 5406124 or 5410180 or 5414299 or 5424576  
or 5428248 or 5435057 or 5444301 or 5452511  
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or 5534467 or 5539251 or 5543657 or 5545923  
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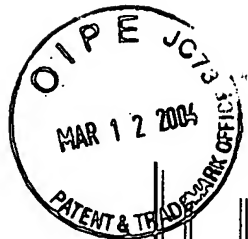
### US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
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Signature

Examiner Name	Date